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SEMICONDUCTOR DEVICE

Group 2700

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[There are no amendments to this patent.]

Claim

A semiconductor device characterized by a construction equipped with a package in which a multiple number of drawn out electrodes are installed on top of an insulation substrate, with the first semiconductor chip connected by wire bonding between the drawn out electrodes described above, whose top surface is installed with a multiple number of protruding electrodes and joined to the substrate described above, and the second semiconductor chip being piled on top of the first semiconductor chip and with its protruding electrodes facing each other on both sides being connected by melt contact so that the degree of integration may be increased.

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